

SEMICONDUCTOR RESIN COMPOSITION, SEMICONDUCTOR RESIN FILM, AND
SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT

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The objective of the present invention is to obtain a semiconductor resin composition having a sufficiently low coefficient of linear expansion of the cured product thereof and a uniform distribution of inorganic particles in the direction of film thickness of a produced semi-cured film thereof. The semiconductor resin composition, which contains (a) an epoxy compound, (b) inorganic particles, (c) a polyimide, and (d) a solvent, is characterized by further containing (e) rubber particles and by the fraction of the (b) inorganic particles in the weight of the total solid fraction resulting from subtracting the weight of the (d) solvent from the total weight of the semiconductor resin composition being 60-92 wt% inclusive.

20 (Figure 1)